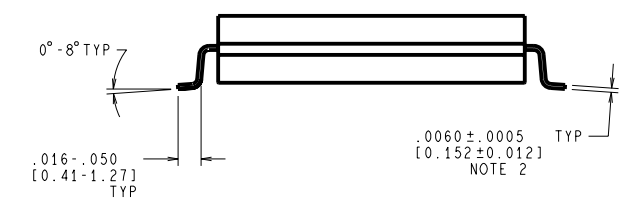
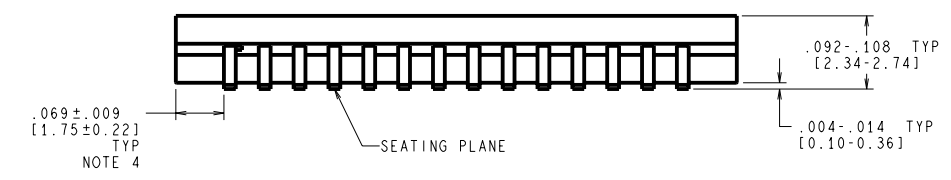
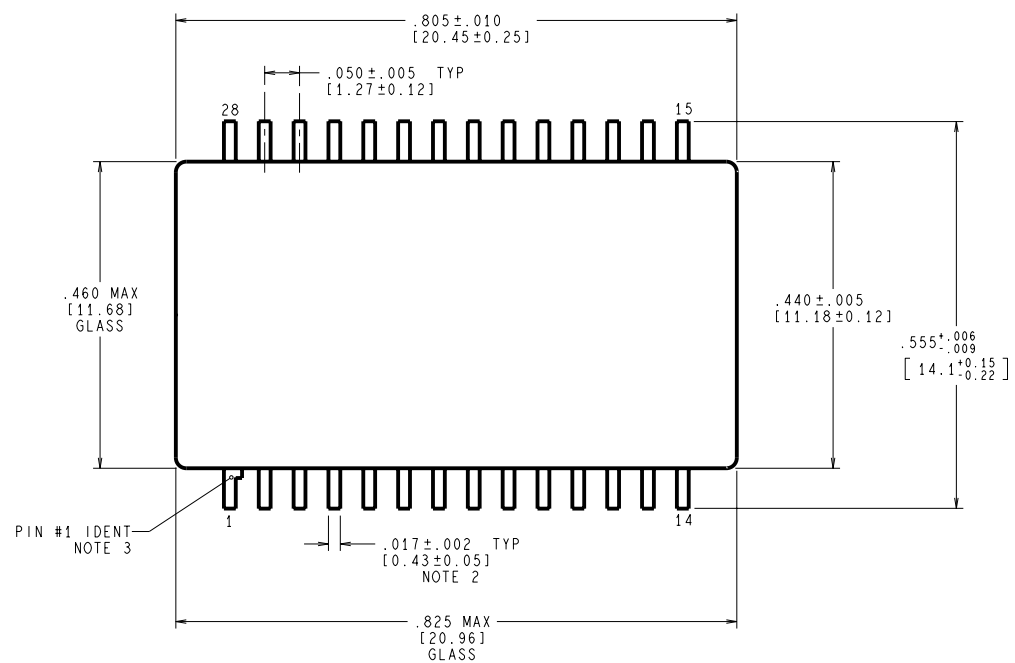


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11153	09/18/95	MS/



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-PRF-38535 TO A MINIMUM THICKNESS OF 200 MICROINCHES/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
- MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES/ 0.08 MILLIMETERS AFTER LEAD FINISH APPLIED.
- LEAD 1 IDENTIFICATION SHALL BE: A TAB ON LEAD 1, EITHER SIDE.
- DIMENSION .069 SHALL BE MEASURED FROM THE EDGE OF THE BASE TO THE EDGE OF THE LEAD.
- NO JEDEC REGISTRATION AS OF 09/18/95.

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS	DATE	National Semiconductor		
DRAWN MARTA SUCHY	09/18/95	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DFTG. CHK.		CERPACK, 28 LEAD, GULL WING		
ENGR. CHK.				
PROJECTION		SCALE	SIZE	DRAWING NUMBER
INCH [MM]		N/A	C	MKT-WG28A
		DO NOT SCALE DRAWING		REV A
		SHEET 1 of 1		